

IMPROVED LED PACKAGE

ABSTRACT

An improved LED package comprises a first stand, a second stand, an
5 LED chip, an epoxy packaging object, wherein the first stand further
comprises a concave bowl section, and a first pin is extended from the
bottom of the first stand, and a second stand is disposed adjacent to the first
stand and keeps a certain distance from the first stand. The LED chip is
disposed in the bowl section at the top of the first stand, and the anode of the
10 LED chip makes use of a conductive metal wire to electrically connect the
second stand. The epoxy packaging object encapsulates the first stand,
second stand, and LED chip inside and just leaves the first and second pins
exposed. A plane perpendicular to the optical path of the light emitted by the
LED chip is disposed on the top surface of the packaging object, and the top
15 surface has more than one circular protrusion to achieve the objective of
enhancing the brightness and uniformity of luminescence.